



A P IFW

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

Ken Chen

Serial No.: 10/058,473

Filed: 01/28/2002

For: ENHANCED ADHESION STRENGTH  
BETWEEN MOLD RESIN AND POLYIMIDE

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)  
) Group Art Unit: 2823  
)  
) Examiner: Toledo, Fernando  
)  
) Confirmation No.: 4186  
)  
) TKHR Docket: 252016-1040  
) Top-Team: 0503-A30594US  
)

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Mail Stop Amendment; Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on December 23, 2004.

Do not  
enter f.h.c. d/5/05

  
Signature - Hui Chin Barnhill

AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

The Office Action mailed October 6, 2004 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

Amendments to the Claims begin on page 2; Remarks begin on page 10 of this paper.